V1.0



## N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V} \,$

### **General Description**

The series of devices use advanced trench gate super junction technology and design to provide excellent Rds(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

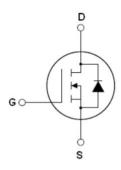
| <b>Features</b> | 3 |
|-----------------|---|
|-----------------|---|

- Optimized body diode reverse recovery performance
- Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

## **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

| V <sub>DS min@Tjmax</sub> | 550  | V  |
|---------------------------|------|----|
| R <sub>DS(ON)TYP</sub> .  | 110  | mΩ |
| $I_D$                     | 23.5 | Α  |
| Qg                        | 24.5 | nC |



Schematic diagram

♦ Intrinsic fast-recovery body diode

## **Package Marking And Ordering Information**

| Device      | Device Package | Marking     |
|-------------|----------------|-------------|
| NCE50NF130V | DFN8*8         | NCE50NF130V |



Table 1. Absolute Maximum Ratings (T<sub>c</sub>=25℃)

| Parameter   | Symbol              | Value   | Unit |
|---|---------------------|---------|------|
| Drain-Source Voltage (Vgs=0V)                                   | V <sub>DS</sub>     | 500     | V    |
| Gate-Source Voltage (V <sub>DS</sub> =0V) ,AC (f>1 Hz)          | Vgs                 | ±30     | V    |
| Gate-Source Voltage (V <sub>DS</sub> =0V) ,DC                   | V <sub>G</sub> s    | ±20     | V    |
| Continuous Drain Current at Tc=25°C                             | I <sub>D (DC)</sub> | 23.5    | А    |
| Continuous Drain Current at Tc=100°C                            | I <sub>D (DC)</sub> | 16.45   | А    |
| Pulsed drain current (Note 1)                                   | DM (pluse)          | 70.5    | А    |
| Maximum Power Dissipation(Tc=25℃)                               | P <sub>D</sub>      | 186     | W    |
| Derate above 25°C   |                     | 1.24    | W/°C |
| Single pulse avalanche current (Note 2)                         | I <sub>AS</sub>     | 6       | Α    |
| Reverse diode dv/dt, $V_{DS} \leq 400 \text{ V,I}_{SD} < I_{D}$ | dv/dt               | 15      | V/ns |
| Drain Source voltage slope,V <sub>DS</sub> ≤400 V               | dv/dt               | 50      | V/ns |
| Operating Junction and Storage Temperature Range                | $T_{J}$ , $T_{STG}$ | -55+175 | °C   |



### **Table 2. Thermal Characteristic**

| Parameter   | Symbol            | Value | Unit  |
|---|-------------------|-------|-------|
| Thermal Resistance, Junction-to-Case (Maximum)    | R <sub>thJC</sub> | 0.80  | °C /W |
| Thermal Resistance, Junction-to-Ambient (Maximum) | R <sub>thJA</sub> | 62    | °C /W |

Table 3. Electrical Characteristics (TA=25°Cunless otherwise noted)

| Parameter                                | Symbol              | Condition  | Min | Тур  | Max  | Unit |
|--|---------------------|--|-----|------|------|------|
| On/off states                            |                     |  | •   |      |      |      |
| Drain-Source Breakdown Voltage           | BV <sub>DSS</sub>   | V <sub>GS</sub> =0V I <sub>D</sub> =250uA                          | 500 |      |      | V    |
| Zero Gate Voltage Drain Current(Tc=25°ℂ) | I <sub>DSS</sub>    | V <sub>DS</sub> =500V,V <sub>GS</sub> =0V                          |     |      | 10   | μA   |
| Zero Gate Voltage Drain Current(Tc=125℃) | I <sub>DSS</sub>    | V <sub>DS</sub> =500V,V <sub>GS</sub> =0V                          |     |      | 300  | μA   |
| Gate-Body Leakage Current                | I <sub>GSS</sub>    | V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V                          |     |      | ±200 | nA   |
| Gate Threshold Voltage                   | V <sub>GS(th)</sub> | V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250uA            | 3   |      | 5    | V    |
| Drain-Source On-State Resistance         | R <sub>DS(ON)</sub> | V <sub>GS</sub> =10V, I <sub>D</sub> =12A                          |     | 110  | 130  | mΩ   |
| Dynamic Characteristics                  |                     |  |     | '    |      |      |
| Gate Resistance                          | Rg                  | F=1MHZ, D-S short  |     | 2    |      | Ω    |
| Input Capacitance                        | C <sub>lss</sub>    | V 50VVV 0V   |     | 1544 |      | pF   |
| Output Capacitance                       | Coss                | $V_{DS}$ =50V, $V_{GS}$ =0V,                                       |     | 630  |      | pF   |
| Reverse Transfer Capacitance             | C <sub>rss</sub>    | F=1MHz   |     | 6.1  |      | pF   |
| Total Gate Charge                        | Qg                  |  |     | 24.5 |      | nC   |
| Gate-Source Charge                       | Q <sub>gs</sub>     | V <sub>DS</sub> =400V,I <sub>D</sub> =12A,<br>V <sub>GS</sub> =10V |     | 11.5 |      | nC   |
| Gate-Drain Charge                        | $Q_{gd}$            |  |     | 6.5  |      | nC   |
| Gate plateau voltage                     | Vgp                 |  |     | 7.7  |      | V    |
| Switching times                          |                     |  |     |      |      |      |
| Turn-on Delay Time                       | t <sub>d(on)</sub>  |  |     | 13   |      | nS   |
| Turn-on Rise Time                        | t <sub>r</sub>      | V <sub>DD</sub> =400V,I <sub>D</sub> =12A,                         |     | 10   |      | nS   |
| Turn-Off Delay Time                      | t <sub>d(off)</sub> | $R_G=4\Omega,V_{GS}=10V$   |     | 58   |      | nS   |
| Turn-Off Fall Time                       | t <sub>f</sub>      |  |     | 9    |      | nS   |
| Source- Drain Diode Characteristics      |                     |  |     |      |      |      |
| Source-drain current(Body Diode)         | I <sub>SD</sub>     | T 0500   |     |      | 23.5 | Α    |
| Pulsed-Source-drain current(Body Diode)  | I <sub>SDM</sub>    | T <sub>C</sub> =25°C   |     |      | 70.5 | Α    |
| Forward on voltage                       | V <sub>SD</sub>     | Tj=25°C,I <sub>SD</sub> =23.5A,V <sub>GS</sub> =0V                 |     | 0.9  | 1.1  | V    |
| Reverse Recovery Time                    | t <sub>rr</sub>     |  |     | 170  |      | nS   |
| Reverse Recovery Charge                  | Qrr                 | Tj=25°C,I <sub>F</sub> 12A,  |     | 1.02 |      | uC   |
| Peak reverse recovery current            | I <sub>rrm</sub>    | di/dt=100A/µs  |     | 12   |      | Α    |

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25  $^{\circ}\text{C}$  ,VDD=50V,VG=10V, R\_G=25 $\Omega$ 



## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

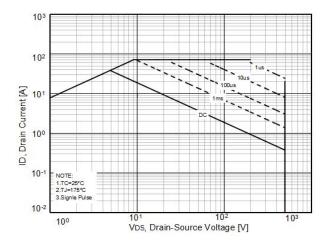


Figure 2. Source-Drain Diode Forward Voltage

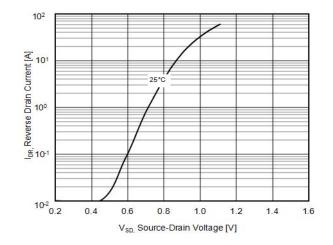


Figure 3. Output characteristics

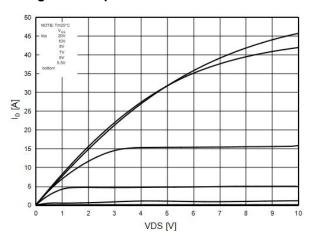


Figure 4. Transfer characteristics

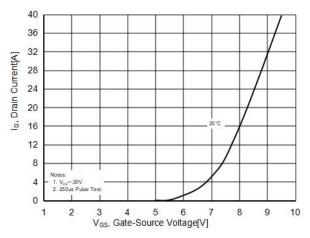


Figure 5. Static drain-source on resistance

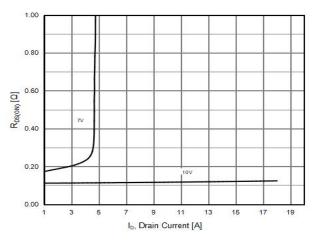
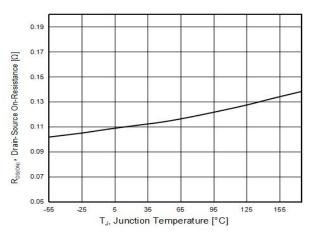


Figure 6. R<sub>DS(ON)</sub> vs Junction Temperature



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Figure 7. BV<sub>DSS</sub> vs Junction Temperature

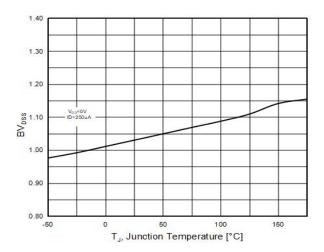


Figure9. Gate charge waveforms

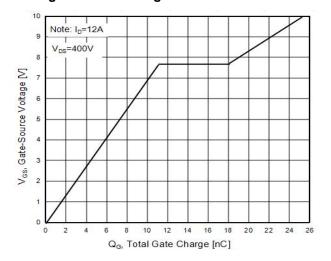


Figure 8. Maximum ID vs Junction Temperature

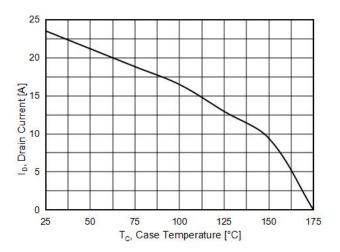
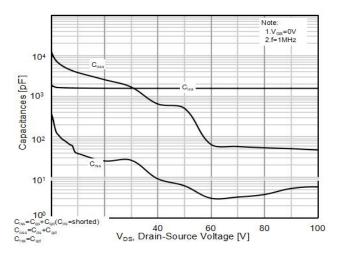


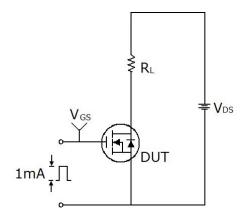
Figure 10. Capacitance

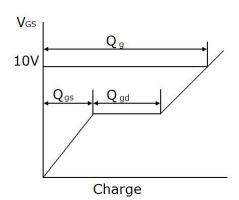




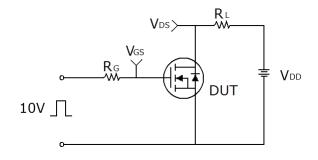
## **Test circuit**

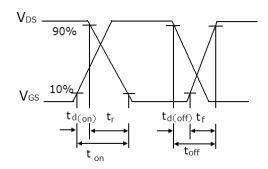
## 1) Gate charge test circuit & Waveform



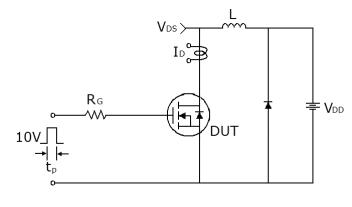


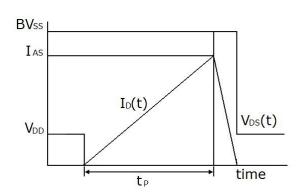
## 2) Switch Time Test Circuit:





## 3) Unclamped Inductive Switching Test Circuit & Waveforms

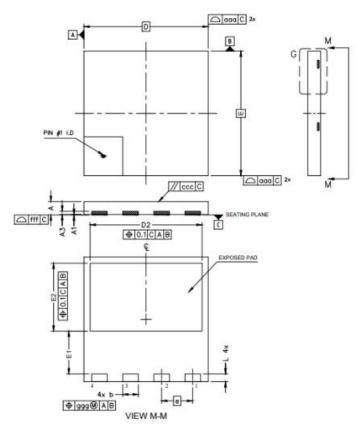




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# **DFN8\*8-B Package Information**



| Symbol | Dimensions In Millimeters |          | Dimensions In Inches |       |  |
|--------|---------------------------|----------|----------------------|-------|--|
| Symbol | Min.                      | Max.     | Min.                 | Max.  |  |
| A      | 0.75                      | 0.95     | 0.030                | 0.037 |  |
| A1     | 0.00                      | 0.05     | 0.000                | 0.002 |  |
| b      | 0.90                      | 1.10     | 0.035                | 0.043 |  |
| A3     | 0.10                      | 0.30     | 0.004                | 0.012 |  |
| D      | 7.90                      | 8.10     | 0.311                | 0.319 |  |
| E      | 7.90                      | 8.10     | 0.311                | 0.319 |  |
| D2     | 7.10                      | 7.30     | 0.280                | 0.287 |  |
| E1     | 2.65                      | 2.85     | 0.104                | 0.112 |  |
| E2     | 4.25                      | 4.45     | 0.167                | 0.175 |  |
| е      | 2.00                      | 2.00 BSC |                      | BSC   |  |
| L      | 0.40                      | 0.60     | 0.016                | 0.024 |  |



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